

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

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Listing of Claims:

Claim 1 (Currently Amended): A connector for connecting a first board to a second board, the connector comprising:
10 at least one conductive media comprising:
a plurality of insulating layers; and
a plurality of conductive layers, wherein each conductive layer is formed between two insulating layers; and
15 ~~a frame comprising a hollow space for holding the conductive media-~~
a lower frame substantially surrounding a first hollow space for holding a lower portion of the conductive media,
the lower frame comprising a lower hook; and
20 an upper frame substantially surrounding a second hollow space for holding an upper portion of the conductive media, the upper frame comprising an upper hook;
wherein when the conductive media is fixed into the first and second hollow spaces, the upper frame and the lower
25 frame are connected to each other by pressing both frames to hook the upper hook and the lower hook.

Claim 2 (Original) : The connector of claim 1 wherein the conductive media is rectangular cubic shaped.

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Claim 3 (Currently Amended) : The connector of claim 1 wherein ~~the frame comprises an upper frame~~ is fixed to the second

board and ~~[[a]]~~ the lower frame is fixed to the first board.

Claim 4 (Currently Amended) : The connector of claim 3 wherein
the upper frame has ~~an upper hook and the lower frame has~~
5 ~~a lower hook for being connected to the upper hook.~~ and
the lower frame when connected are fixed between the first
board and the second board.

Claim 5 (Currently Amended) : The connector of claim 1 wherein
10 the first board is fixed to the lower frame through a top
plug connection.

Claim 6 (Currently Amended) : The connector of claim 3 wherein
[[the]] an upper side of the conductive layer is connected
15 to a goldfinger on the second board through a metal
connecting point on the upper frame, and [[the]] a lower
side of the conductive layer is connected to a goldfinger
on the first board through a metal connecting point on the
lower frame, in order to transmit electric signals between
20 the first board and the second board.

Claim 7 (Currently Amended) : The connector of claim 1 wherein
the upper and lower frames ~~frame is a~~ are plastic frame.

25 Claim 8 (Currently Amended) : The connector of claim 1 wherein
[[the]] an upper side of the conductive layer is connected
to a goldfinger on the second board, and [[the]] a lower
side of the conductive layer is connected to a goldfinger
on the first board, in order to transmit electric signals
30 between the first board and the second board.

Claim 9 (Original) : The connector of claim 1 wherein the second

board is a printed circuit board.

Claim 10 (Original) : The connector of claim 1 wherein the first board is an interface card.

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Claim 11 (Original) : The connector of claim 1 wherein the conductive layers are formed by conductive ceramic particles.

10 Claim 12 (Original) : The connector of claim 1 wherein the conductive layers are formed by conductive metal particles.

Claim 13 (Original) : The connector of claim 1 wherein the conductive layers are conductive metal lines.

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Claim 14 (Original) : The connector of claim 1 wherein the insulating layers are formed by insulating rubber.

20 Claim 15 (Original) : The connector of claim 1 wherein the insulating layers are formed by insulating ceramic materials.

25 Claim 16 (New) : The connector of claim 1 wherein at least a portion of the first hollow space extends through the lower frame such that a lower side of the lower portion of the conductive media is exposed for direct electrical connection between the conductive layers and metal connections on the first board.

30 Claim 17 (New) : A connector for electrically connecting a first circuit board to a second circuit board, the connector comprising:

at least one conductive media comprising:

a plurality of insulating layers; and

a plurality of conductive layers, wherein each
conductive layer is formed between two insulating
layers;

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a plastic lower frame fixed to the first circuit board and
defining a first hollow space extending through the lower
frame for holding a lower portion of the conductive media
in electrical contact with metal on the first circuit
board, the lower frame comprising a lower hook; and

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an plastic upper frame fixed to the second circuit board
and defining a second hollow space extending through
the upper frame for holding an upper portion of the
conductive media in electrical contact with metal on
the second circuit board, the upper frame comprising
an upper hook hooked to the lower hook for physically
connecting the upper and lower frames;

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wherein the connected upper and lower frames are disposed
between the first and second circuit boards.

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Claim 18 (New) : The connector of claim 17 wherein the first
circuit board is fixed to the lower frame through a top
plug connection.